



# Fate of Fluorine Determination in Exhaust from NF<sub>3</sub>-Based CVD Chamber Cleans

Victor Vartanian, Brian Goolsby, Laura Mendicino,  
Paul Thomas Brown, Dan Babbitt, Jason Vires, Brian Raley

*Motorola, DigitalDNA™ Laboratories*

3501 Ed Bluestein Blvd  
Austin, TX 78721

Curtis Laush, Thomas Huang

*URS Radian*

15705 Long Vista Drive  
Austin, TX 78728

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# Overview

- I. Project Objectives
- II. Fluorine Emission Regulatory Issues
- III. AMAT Remote Clean™ Technology
- IV. Experimental Methodology
- V. Data Analysis
- VI. Summary
- VII. Future Work



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# Project Objectives

- Determine effect of increased F<sub>2</sub> in exhaust system and effect on emissions treatment infrastructure
- Quantify F<sub>2</sub> in segregated acid exhaust duct (FRP) downstream of tool equipped with Remote Clean™
- Measure emissions using RGA, FTIR, FCS
  - Quantify F<sub>2</sub> emissions and F<sub>2</sub> to HF conversion efficiency
    - as a function of H<sub>2</sub>O-to-F<sub>2</sub> ratio (damper position)
    - reaction time (damper position and sampling point)
- Evaluate FCS technology as alternative to RGA/impinger/IC
- Perform materials compatibility study of exhaust duct polymeric coupons placed in exhaust stream (F<sub>2</sub>, HF)
- Determine if OF<sub>2</sub> is produced
- Calculate fluorine mass balance





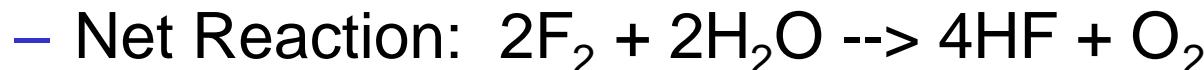
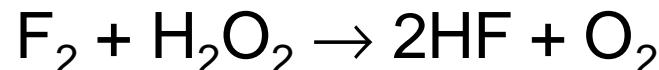
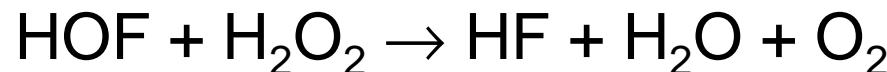
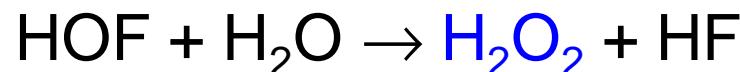
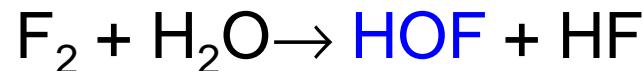
# Fluorine Emission Regulatory Issues

- $NF_3$  chamber clean  $F_2$  emissions are 6X  $C_2F_6$ 
  - impacts on scrubber efficiency, fluoride ion in wastewater
- $F_2$  is not a HAP as defined by EPA in 40 CFR 63
  - $F_2$  regulated by states (TNRCC) New Source Review (NSR)
  - NSR insures ground level concentrations are below ESL
- ESL (Effects Screening Level) evaluates:
  - potential health effects, odor potential, potential effects on vegetation, corrosion potential → *not ambient air standards*
- ESL for  $F_2$  is very low--2  $\mu\text{g}/\text{m}^3$  (arsine is 1.6  $\mu\text{g}/\text{m}^3$ )
- $F_2$  is a Toxic Release Inventory (TRI) reportable chemical if used or generated above a certain level
  - current thresholds: 10,000 lb used or 25,000 lb generated
  - ⇒ *included are  $F_2$  from  $NF_3$  cleans and etch emissions*

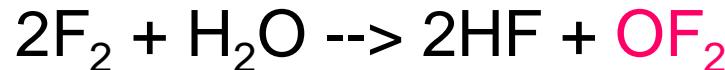


## Fluorine Reactivity

- Highly electronegative, strongest oxidizer
- Small atomic radius
- Reactivity due to small size (0.71Å) high nuclear charge
- Thermodynamically favored reaction with water:



- In caustic media:

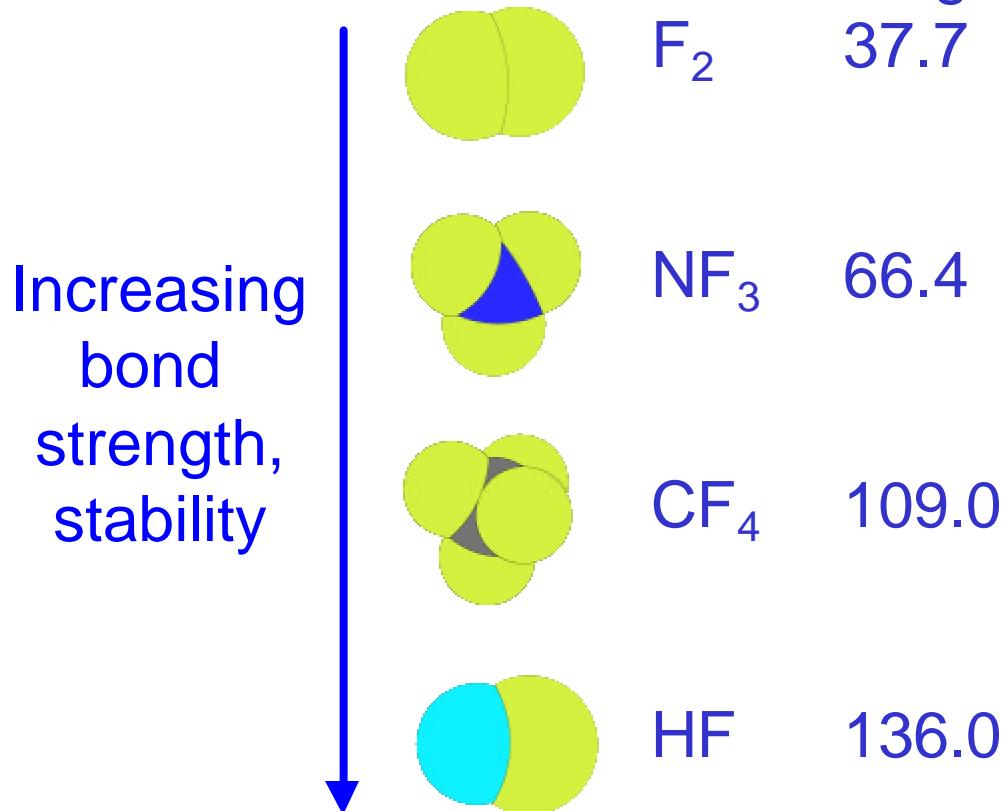


- $OF_2$  production increases in alkaline solutions (esp. NaOH)



## Fluorine Reactivity

### Bond Dissociation Energies (kcal/mol)

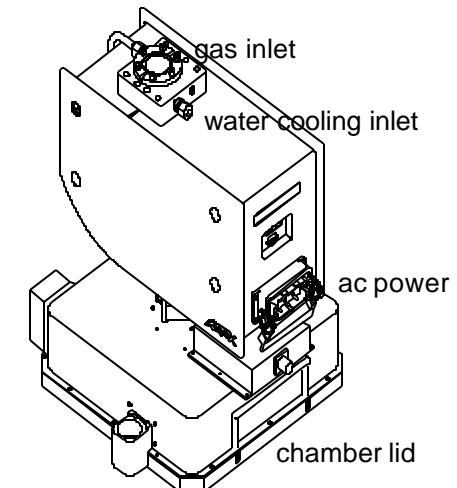


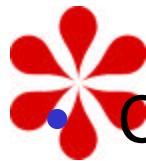


# AMAT Remote Clean™ Technology

- Compact, lid-mounted, point of use
- Low-field toroidal microwave (2.45 GHz)
- No consumables
- Converts 95-99% NF<sub>3</sub> to atomic fluorine
- No ion bombardment
  - increased chamber kit longevity
- F<sub>2</sub> cleans remote chamber areas
  - increased time between wet cleans
- Faster clean times (30%--DxZ, 65%--DxL)
  - increased throughput
- Improved film deposition uniformity
- Uses up to 50% NF<sub>3</sub> (Ar balance)
  - 0.1 to 4.0 slm total gas flow, 1-8 Torr

Remote Clean™ Unit  
on DxZ Chamber





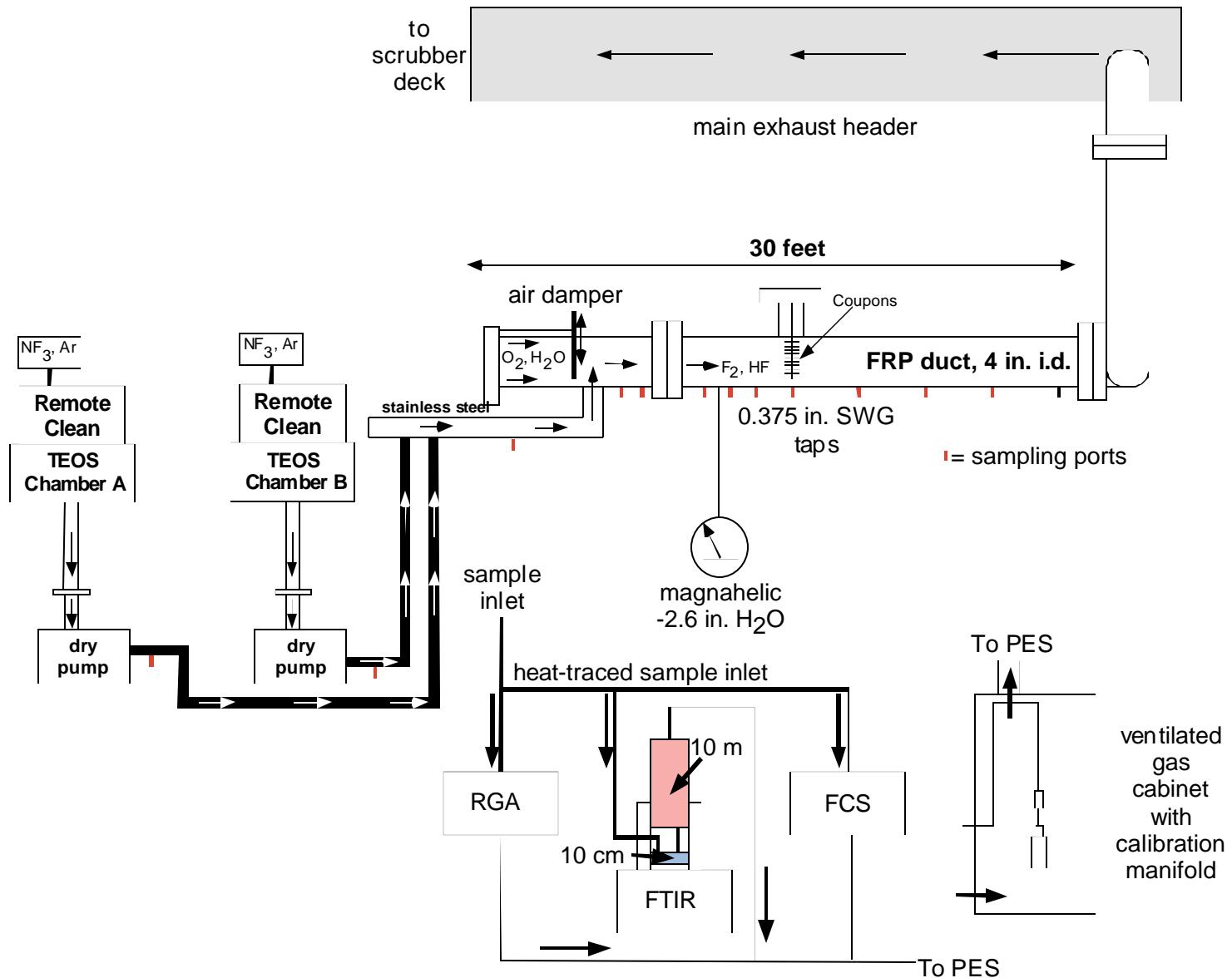
# Experimental Methodology

Continuous air flow measurements made using velocimeter

- Mechanical pump purge regulated by MFC
- Ambient air (45% R.H., 6800 ppm H<sub>2</sub>O) introduced to duct
  - Increased H<sub>2</sub>O in duct using humidifier
- Damper controls H<sub>2</sub>O-to-F<sub>2</sub> ratio and reaction time
  - H<sub>2</sub>O-to-F<sub>2</sub> ratio ranges from 4.4-to-1 to 45.8-to-1
  - Reaction time ranges from 0.15 to 5 sec
- Analytical: extractive FTIR, atmospheric pressure RGA, FCS
  - Pneumatically switched dual-cell FTIR (10 cm, 10 m)
  - All instruments have common sampling point
  - Heat-traced and purged transfer lines (except FCS)
  - RGA and FCS calibrated using “dynamic dilution”
- Clean recipe used: 700 sccm NF<sub>3</sub>, 1400 sccm Ar, 900 sec



## Fluorine Test Lateral Schematic



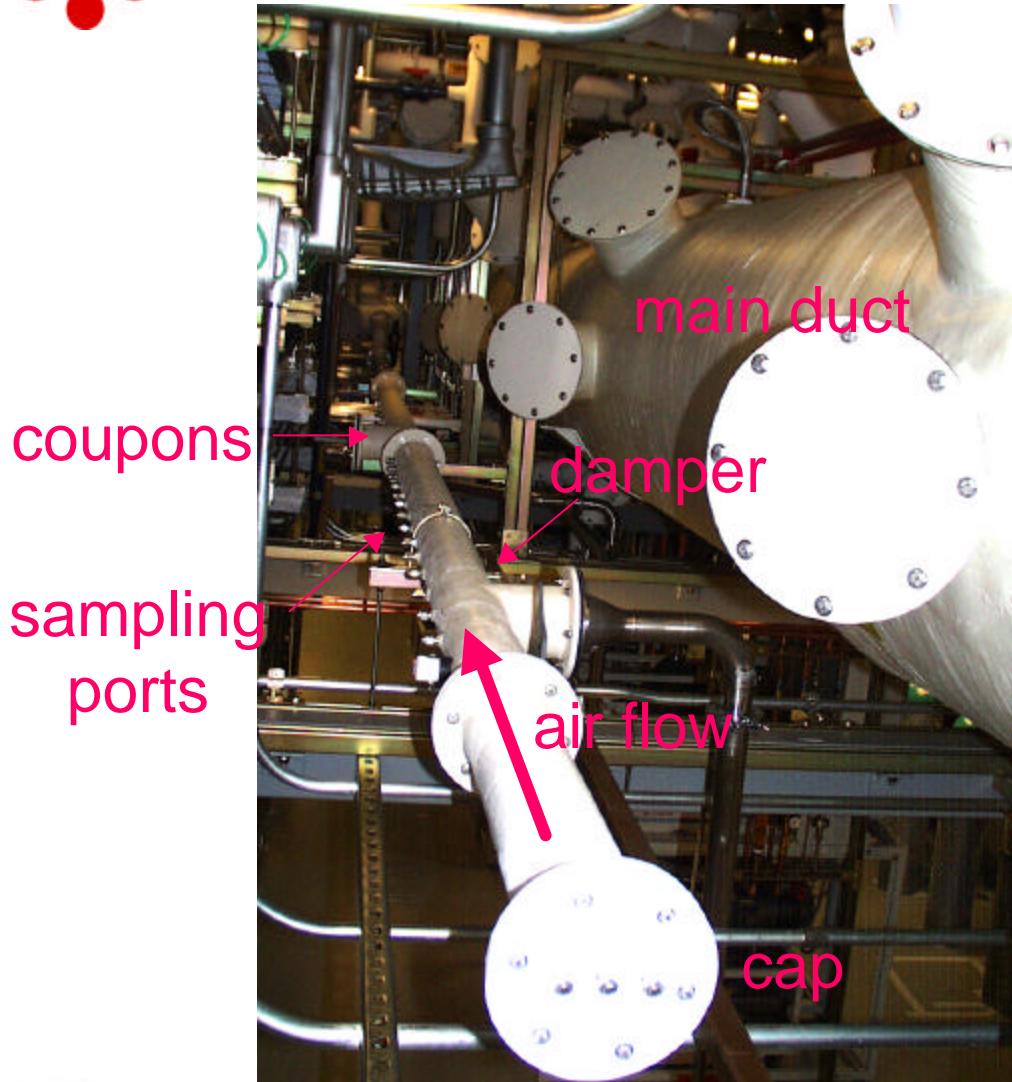
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## FRP Test Lateral



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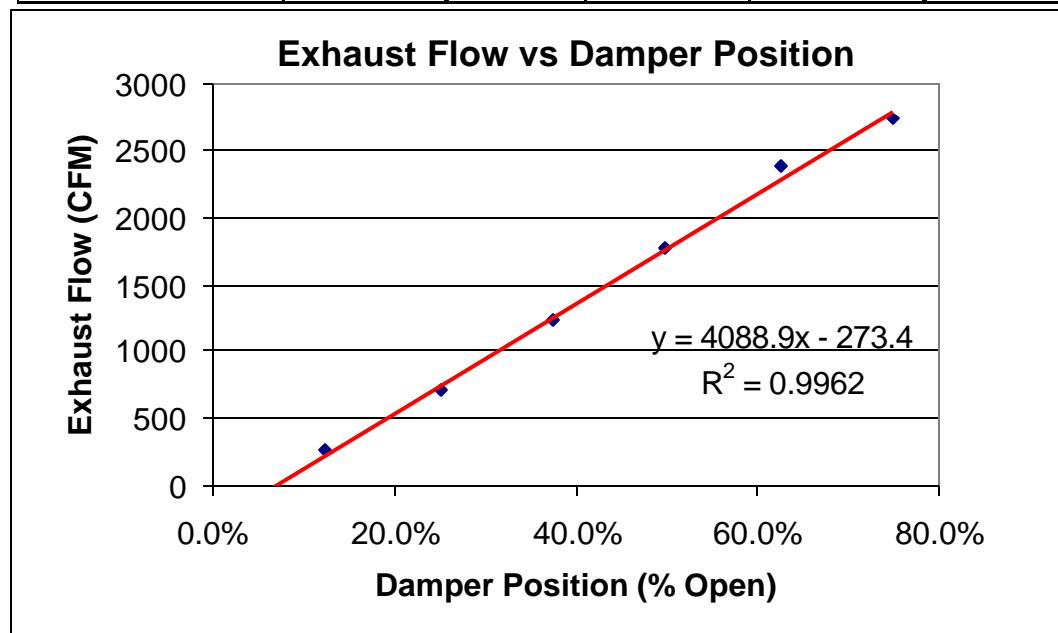
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# Air Flow Measurements

Damper Position (% Open)	Velocity (feet/min)	CFM	Liter/min	Negative Static Pressure (in. H <sub>2</sub> O)	*H <sub>2</sub> O-to- fluorine ratio
0.0%	NA	NA	NA	2.600	NA
12.5%	262	23	651	2.600	4.43
25.0%	705	62	1756	2.536	11.94
37.5%	1243	109	3087	2.556	20.99
50.0%	1773	155	4390	2.498	29.85
62.5%	2383	209	5919	2.576	40.25
75.0%	2727	238	6740	2.430	45.83
100.0%	2721	238	6740	2.439	45.83

\*Based on  
45% r.h.,  
6800 ppmv  
H<sub>2</sub>O in air



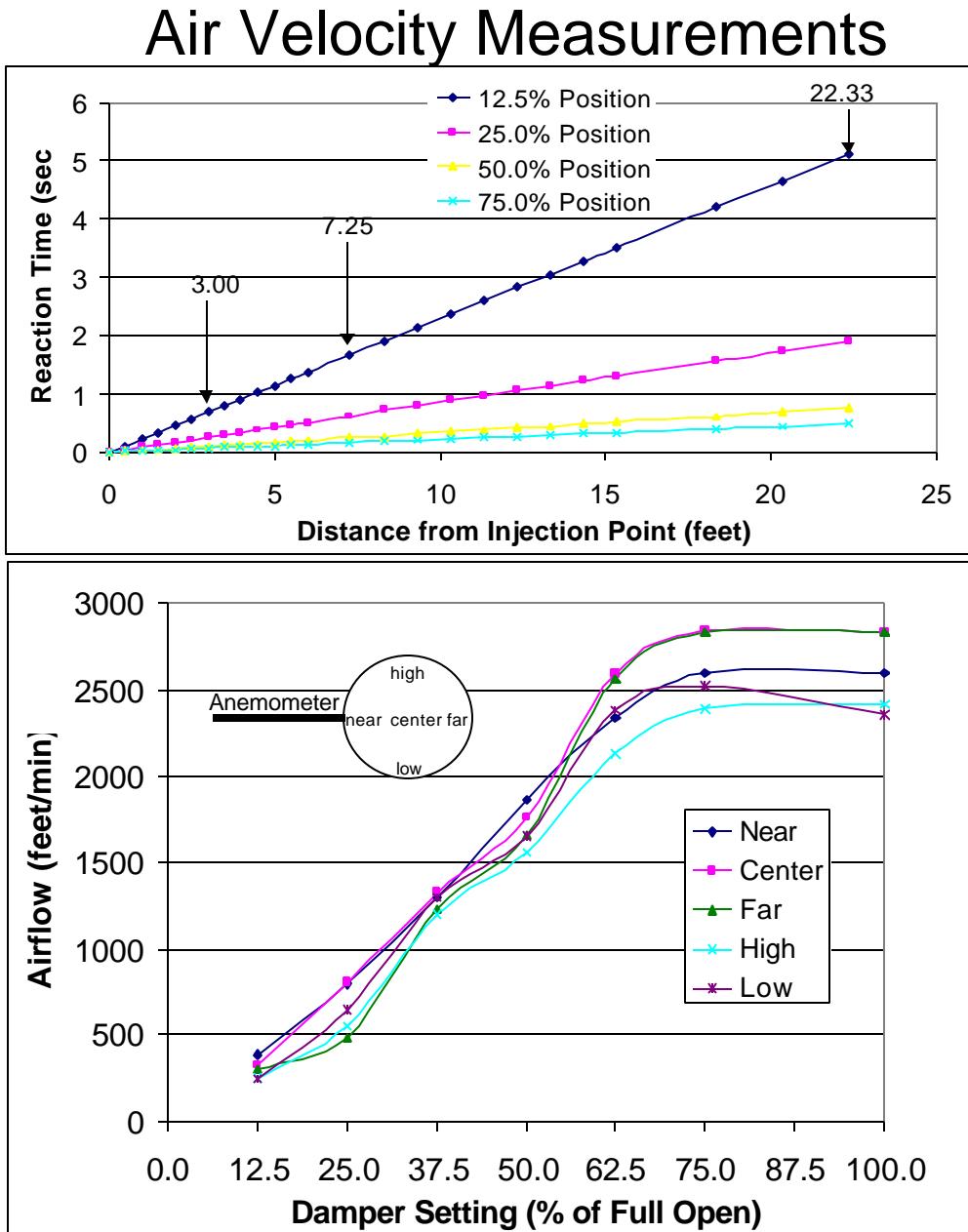
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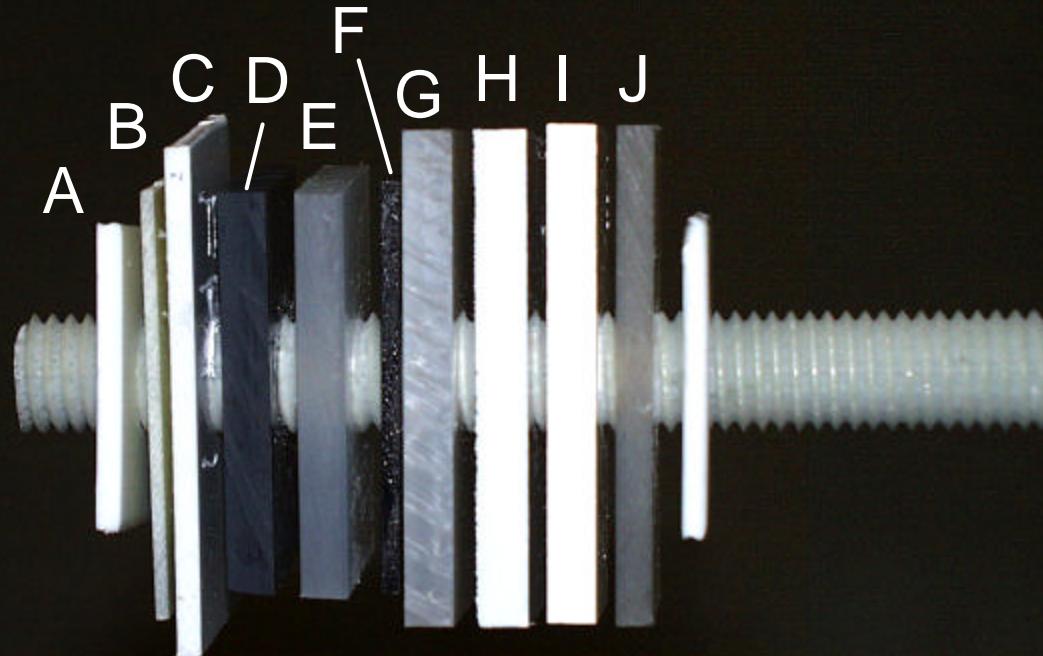
## Reaction Time as a Function of Distance from F<sub>2</sub> Injection Point





## Duct Material Evaluation

Coupons placed in exhaust stream



Perform  $F_2$  exposure analysis  
HF immersion  
---> $\Delta$  mass

- A: PTFE (Teflon)
- B: FRP (Fiberglass Reinforced Plastic)
- C: FRPP (Flame Retardant Polypropylene)
- D: PVC (Polyvinylchloride)
- E: PP (Polypropylene)
- F: ATS (Air Tight Systems brand of FRP)
- G: PVDF (Polyvinylidene fluoride or Kynar)
- H: Flametec (KYTEC PVDF)
- I: Corzan
- J: Halar

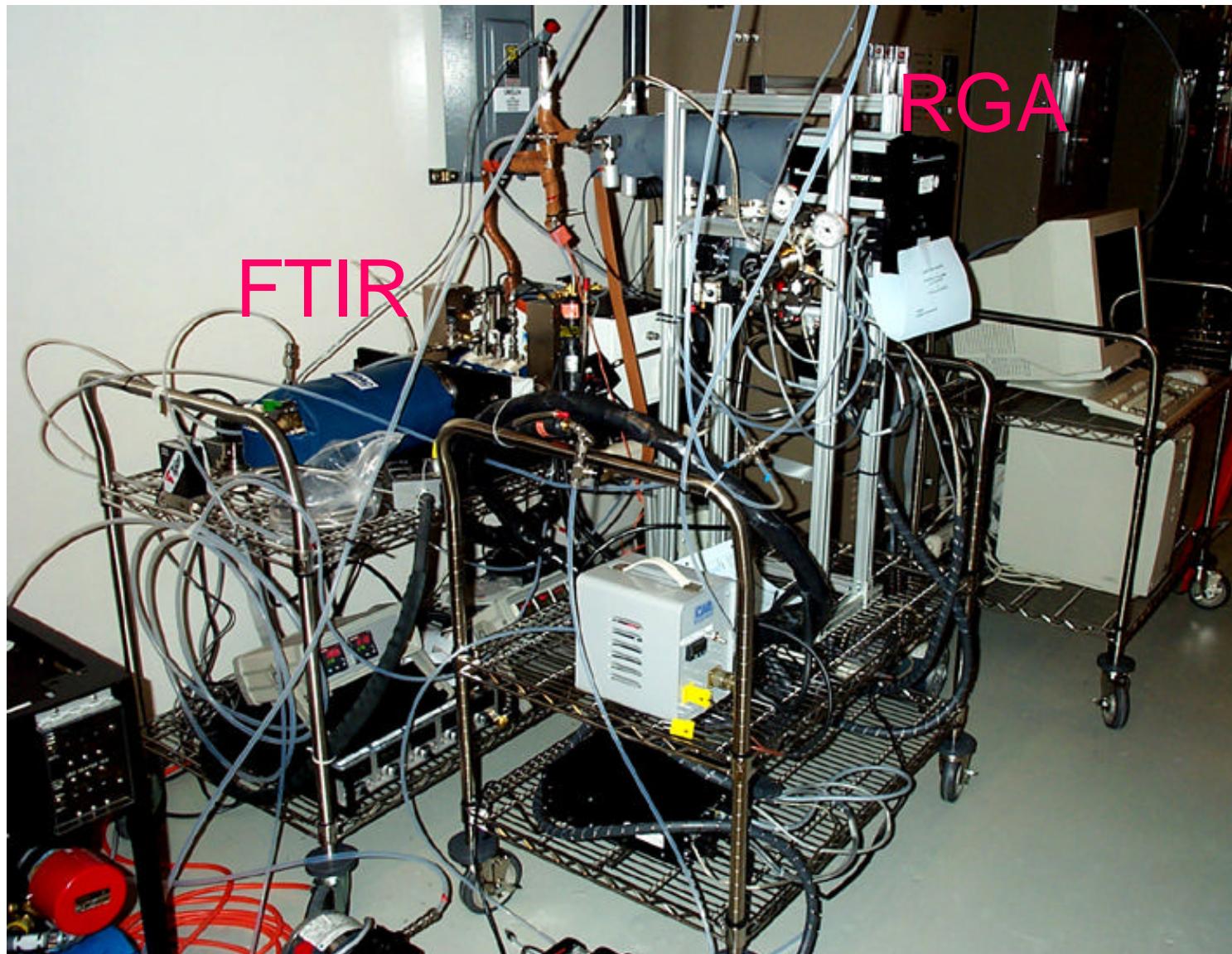


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# FTIR, RGA Sampling Arrangement



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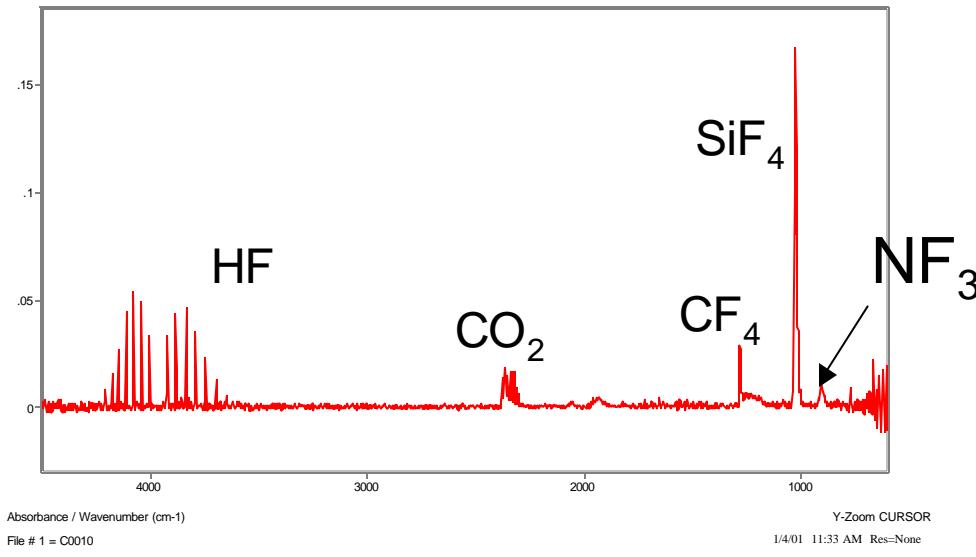


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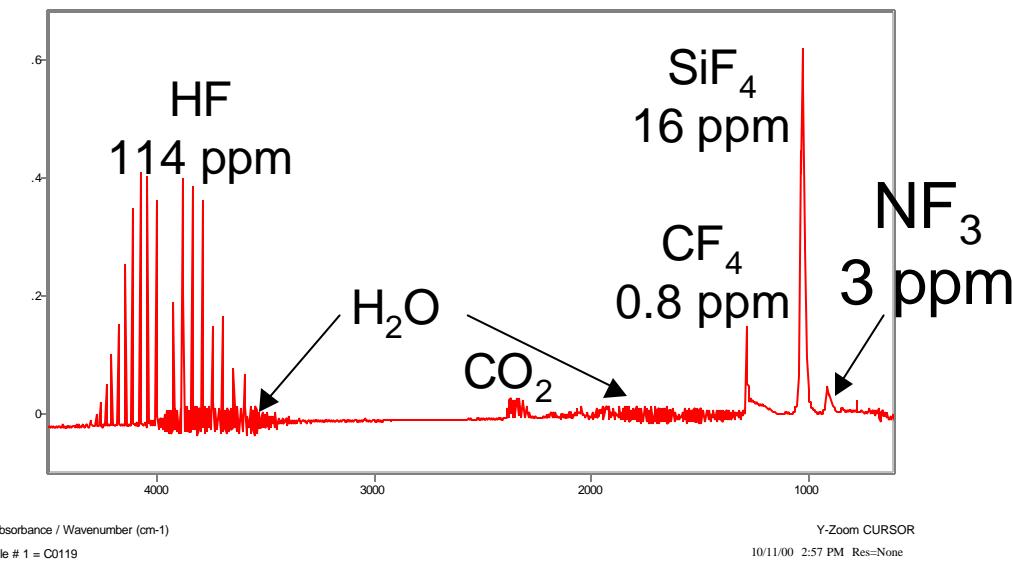


## FTIR $\text{NF}_3$ Chamber Clean Emissions

Stainless  
steel duct  
10 cm



FRP duct  
10 m

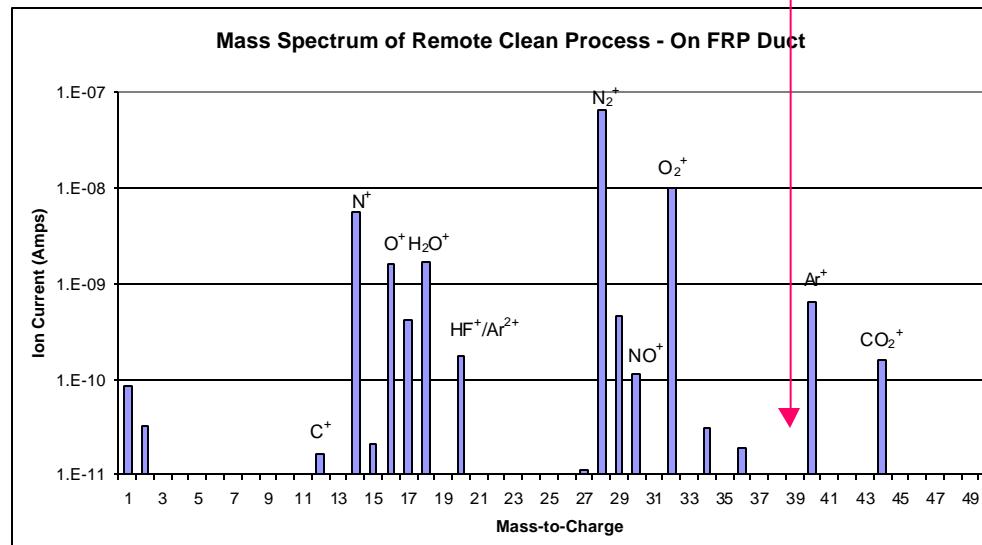
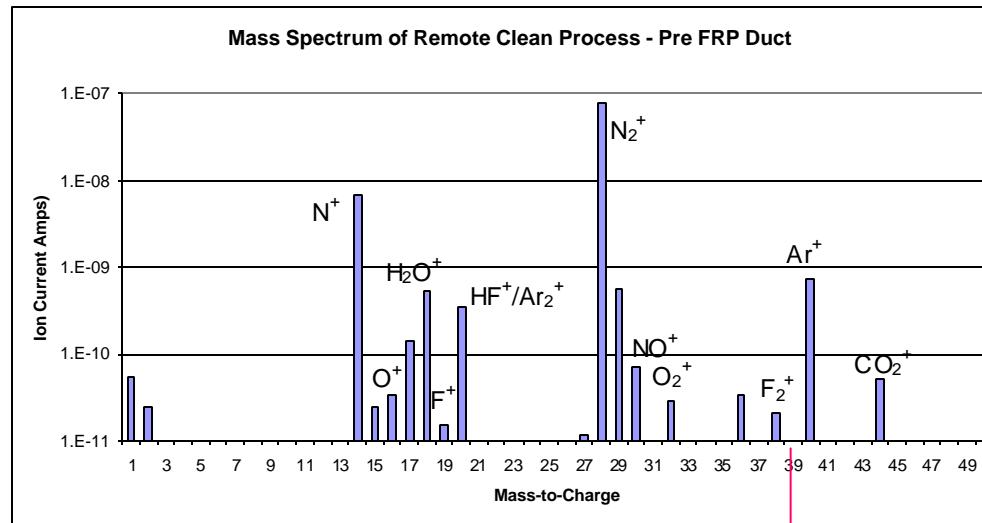




# RGA NF<sub>3</sub> Chamber Clean Emissions

Post-pump  
measurement

Higher  
CO<sub>2</sub>, H<sub>2</sub>O



FRP duct  
measurement  
--F<sub>2</sub> below  
detection limit



# URS Radian Fluorine Chemical Sensor



cart system/  
laptop



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signal conditioner

variable  
transformer

PMT

organic  
substrate

preamp





## URS Radian Fluorine Chemical Sensor (FCS)

- Real-time, solid-state gas sensing device with ppb-level sensitivity and wide measurement range
- Applicability ranges from ambient air (scrubber) to dry nitrogen (tool effluent) characterizations
- Based on the chemical interaction of F<sub>2</sub> with organic substrate; no known cross interferents
- Fast response, small footprint, no vacuum system required
- Calibration performed at constant flow



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# FCS Operation and Performance Specifications

<b>Measurement range</b>	<b>0 to percentage levels (&gt;10000 ppmv)</b>
<b>Measurement precision</b>	<b>± 2%</b>
<b>Minimum detection limit</b>	<b>10 ppbv</b>
<b>Detector response time</b>	<b>msec</b>
<b>Sample cell operating pressures</b>	<b>mTorr to several atm</b>
<b>Footprint</b>	<b>cell/detector: 12"x 3"x 3"</b>
<b>Weight</b>	<b>cell/detector: 2 lbs</b>
<b>Electrical requirements</b>	<b>24 VDC</b>
<b>Applicable sample matrices</b>	<b>Ambient air, tool effluent (low pressure or N<sub>2</sub> diluted), water saturated air or nitrogen streams (wet scrubber outlets)</b>
<b>Chemical interferences</b>	<b>None observed for mixtures containing SiF<sub>4</sub>, HF, O<sub>2</sub>, Cl<sub>2</sub>, HCl, PFCs and H<sub>2</sub>O</b>

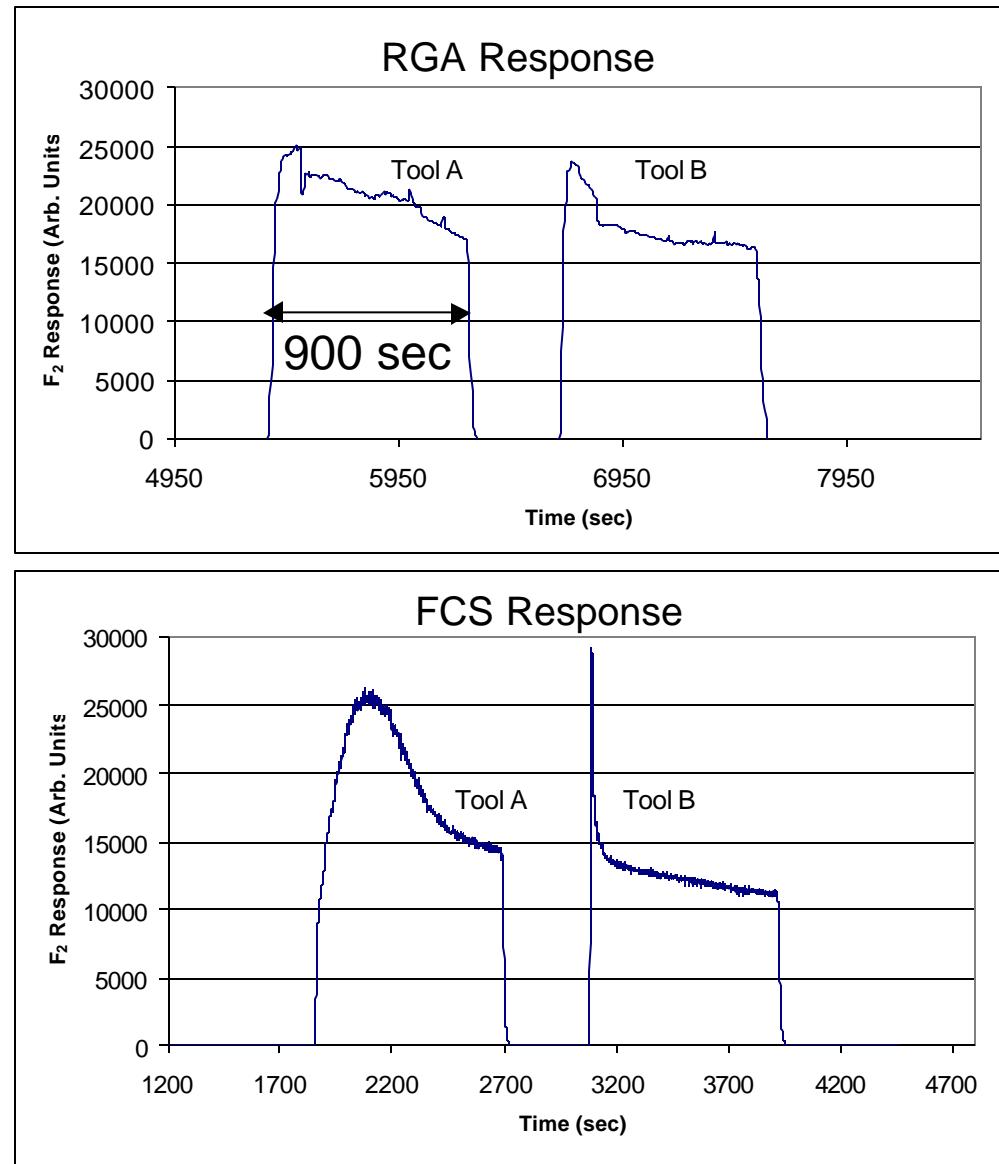


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# RGA and FCS Comparison During Clean



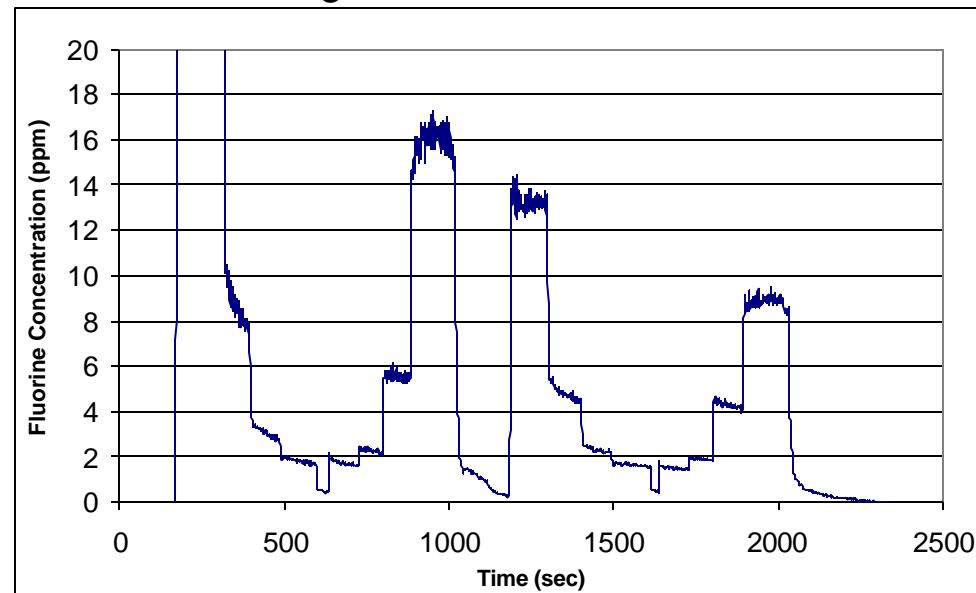
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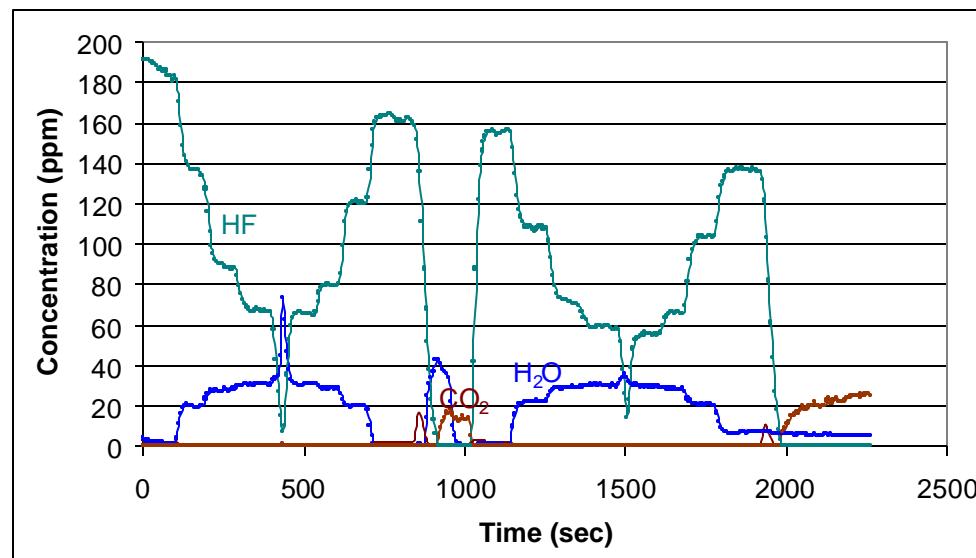


# FCS and FTIR NF<sub>3</sub> Chamber Clean Emissions

FCS



FTIR



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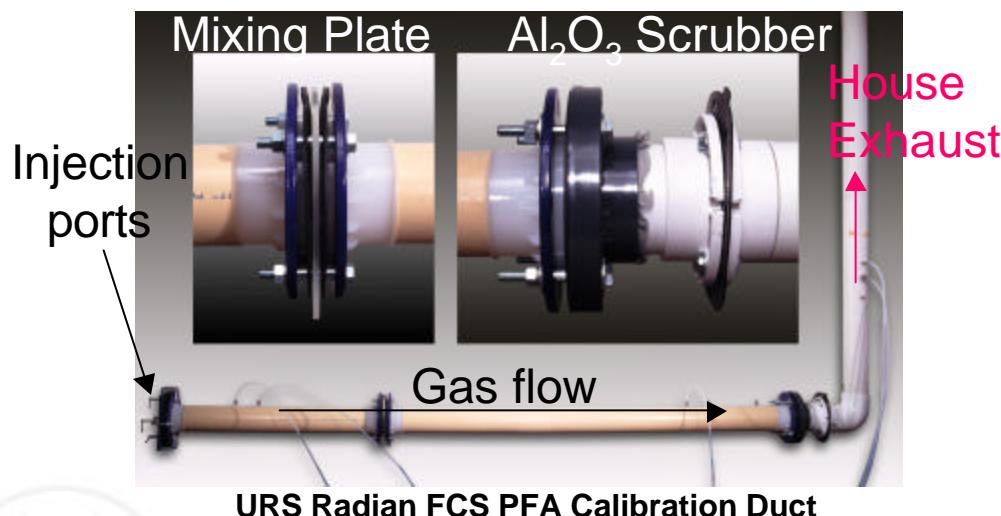


# Analytical Calibration of Fluorine

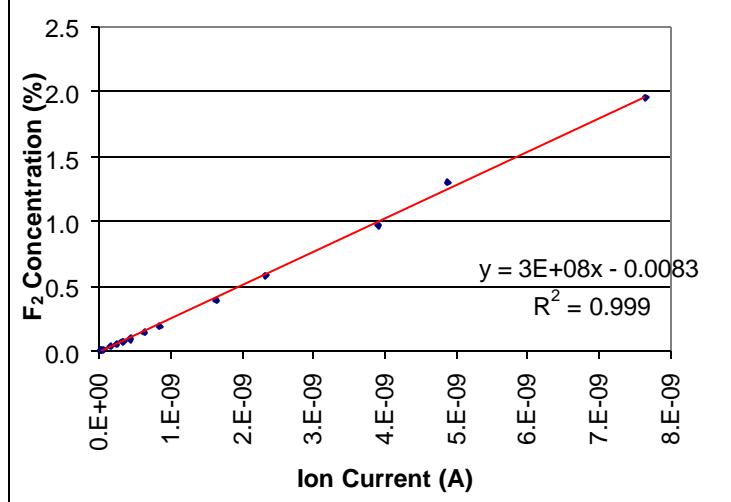
3 analyte panels,  
1 N<sub>2</sub> panel



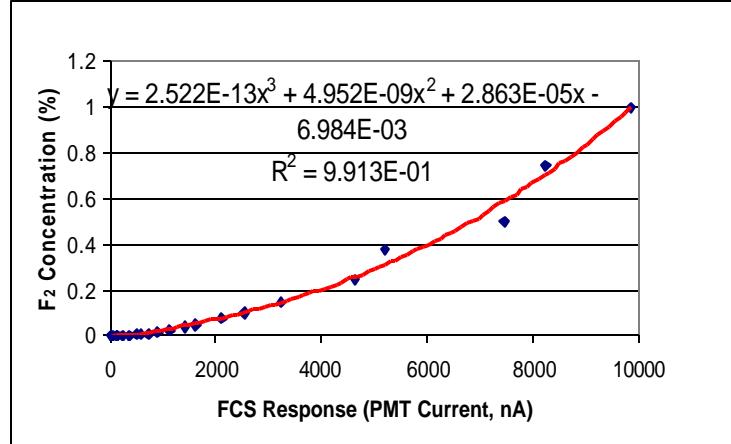
Exhausted Gas Cabinet "Dynamic Dilution" Manifold



## RGA F<sub>2</sub> Calibration Curve



## FCS F<sub>2</sub> Calibration Curve



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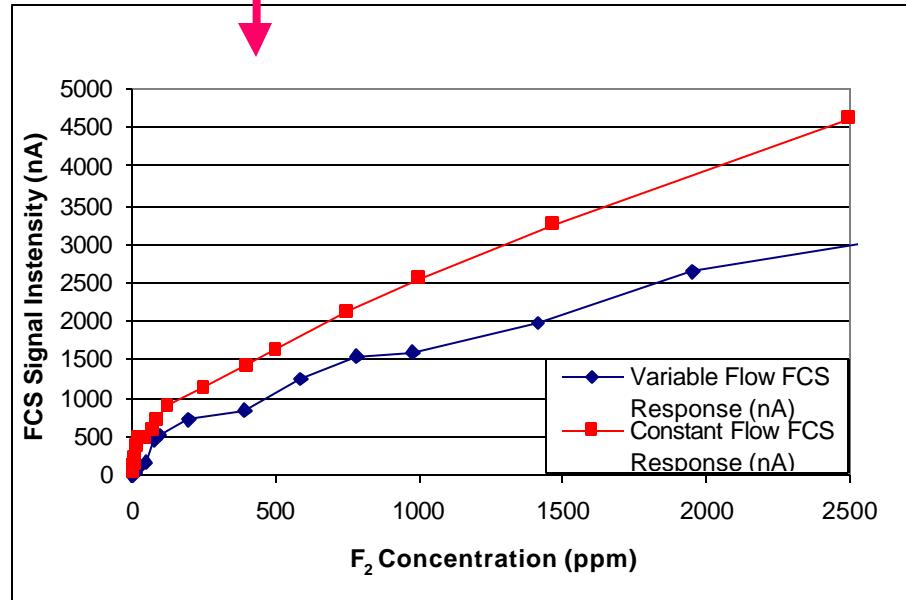
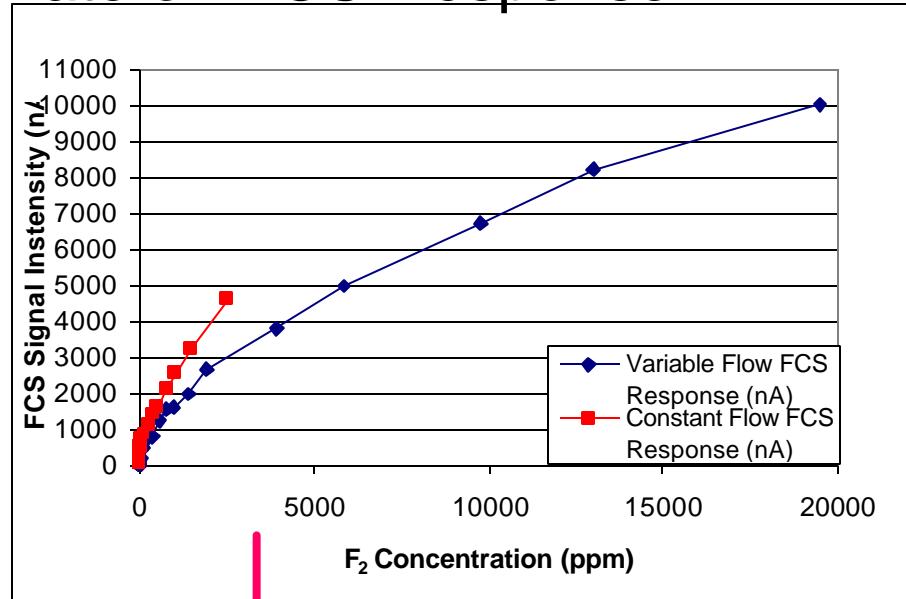
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Conventional calibration--  
gas delivered directly to FCS;  
gas flow through FCS varies

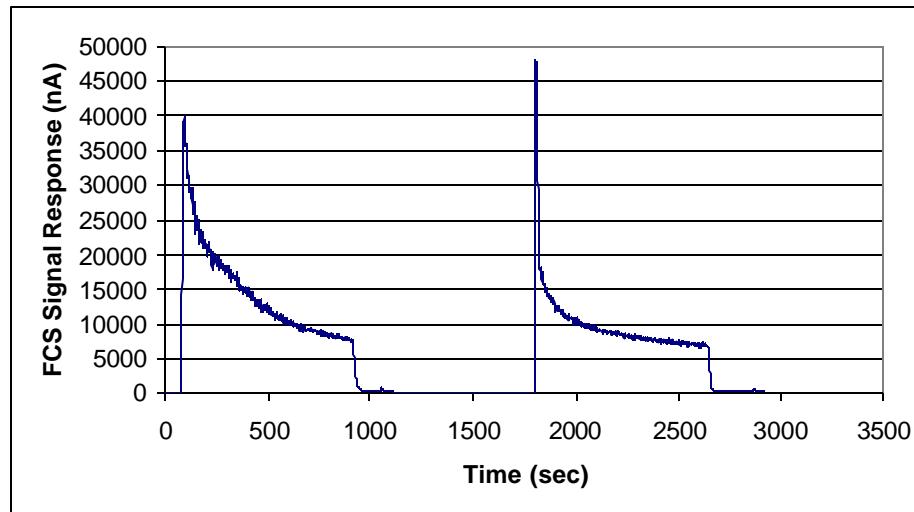
F <sub>2</sub> Flow (sccm)	Nitrogen Flow (sccm)	Total Gas Flow (sccm)	Actual %	ppm
5	4995	5000	0.00195	19.5
10	4990	5000	0.0039	39.0
20	4980	5000	0.0078	78.0
25	4975	5000	0.00975	97.5
25	2475	2500	0.0195	195.0
50	2450	2500	0.039	390.0
60	1940	2000	0.0585	585.0
80	1920	2000	0.078	780.0
100	1900	2000	0.0975	975.0
75	925	1000	0.14625	1462.5
100	900	1000	0.195	1950.0
200	800	1000	0.39	3900.0
300	700	1000	0.585	5850.0
500	500	1000	0.975	9750.0
500	250.0	750	1.3	13000.0
500	0.0	500	1.95	19500.0



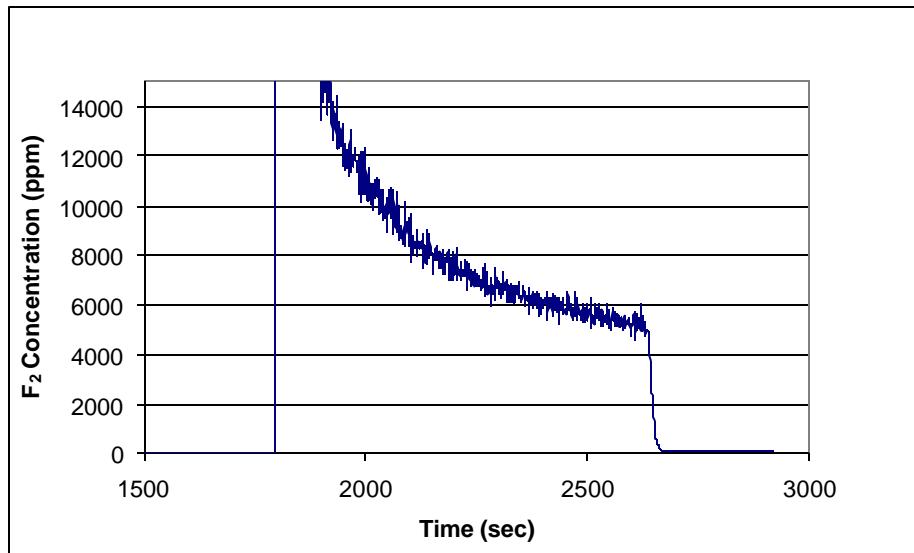


# FCS Quantitation of F<sub>2</sub> Emissions in Stainless Duct

Two consecutive cleans



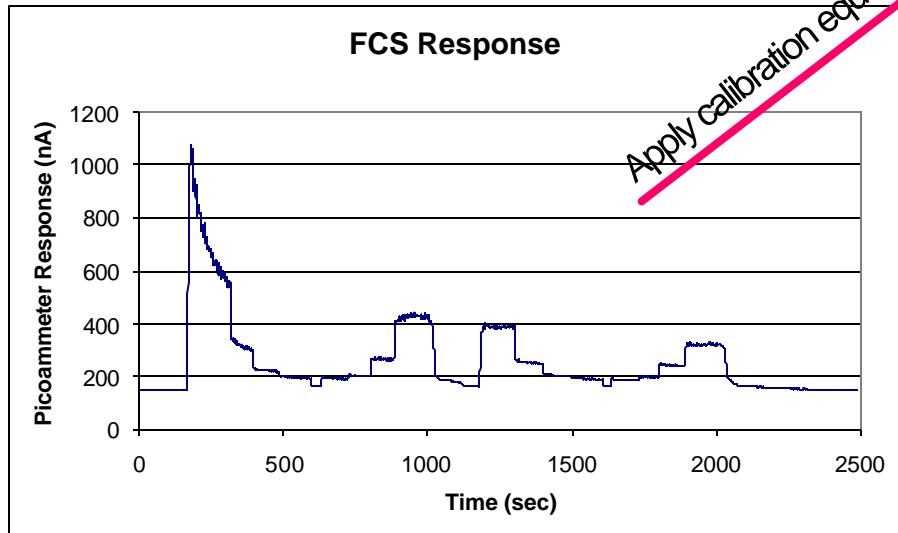
Calibration equation converts nA to ppm



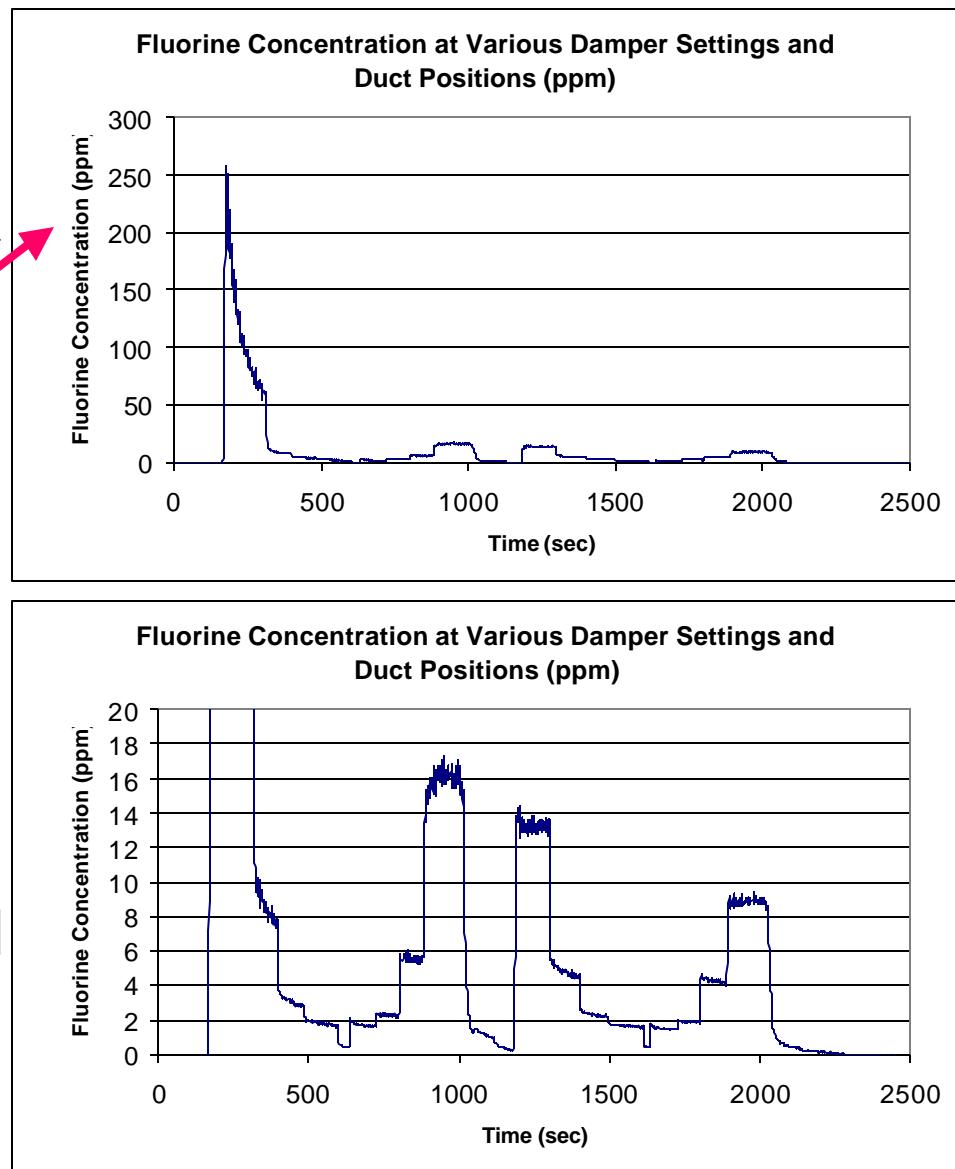
7500 ppm (avg.) =  
~700 sccm F<sub>2</sub>  
from a 700 sccm  
NF<sub>3</sub> process



# FCS Quantitation of F<sub>2</sub> Emissions in FRP Duct



Expanded



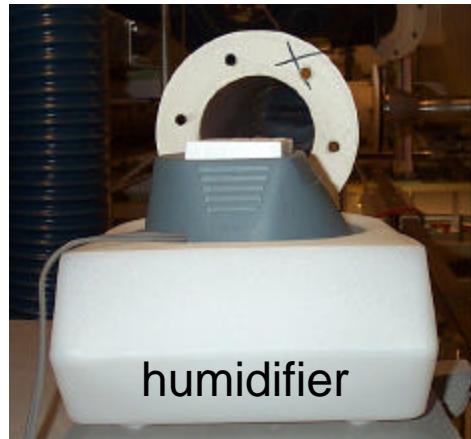
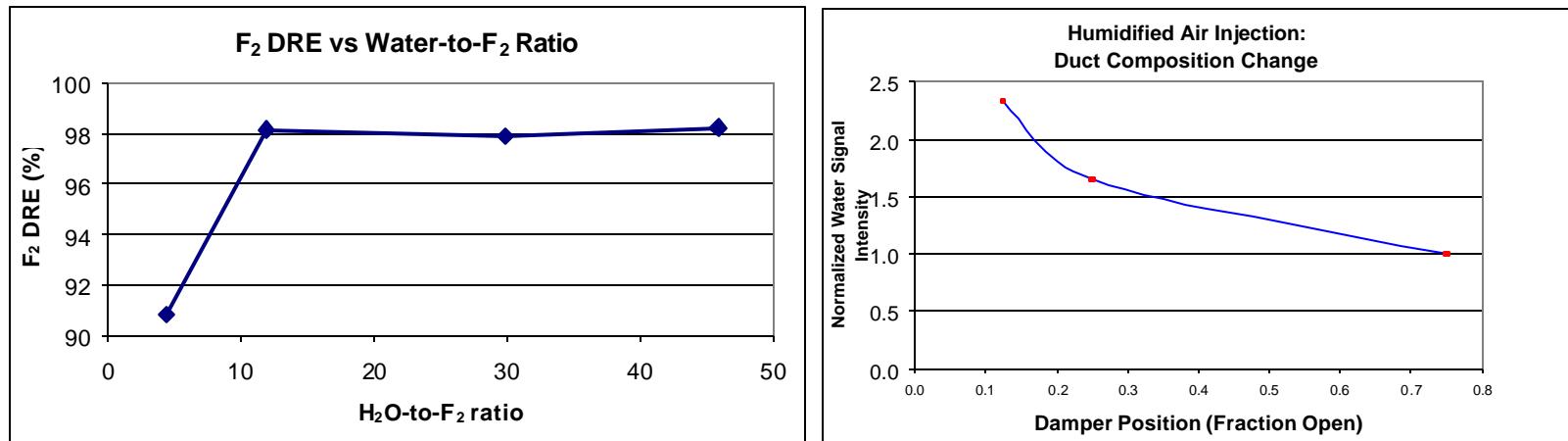
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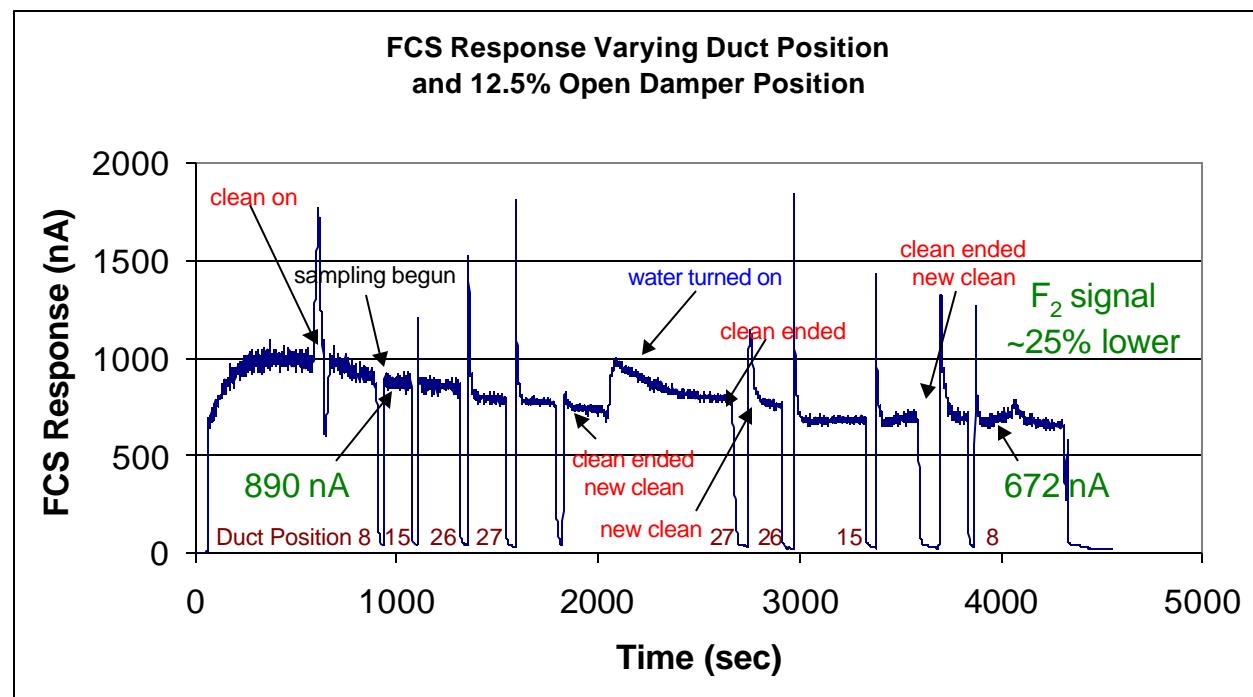
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# Effect of Water Concentration on F<sub>2</sub> DRE



H<sub>2</sub>O concentration increased 15 to 168% depending on damper position



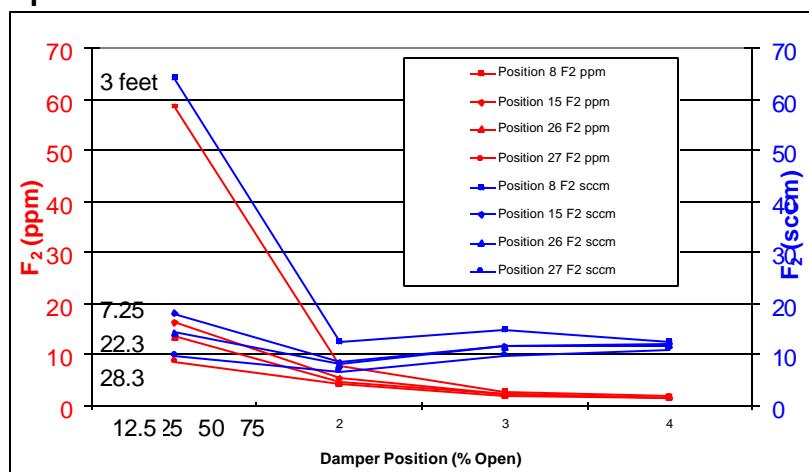


# Fluorine DRE Summary

Damper Setting (% Open)	3.0 feet Downstream			7.25 feet Downstream			22.3 feet Downstream			28.3 feet Downstream		
	Average Flow (slm)	Maximum expected F <sub>2</sub> Concentration by Dilution (ppmv)	Average F <sub>2</sub> Measured (ppmv)	ΔF <sub>2</sub> (%)	Average Flow (slm)	Maximum expected F <sub>2</sub> Concentration by Dilution (ppmv)	Average F <sub>2</sub> Measured (ppmv)	ΔF <sub>2</sub> (%)	Average Flow (slm)	Maximum expected F <sub>2</sub> Concentration by Dilution (ppmv)	Average F <sub>2</sub> Measured (ppmv)	ΔF <sub>2</sub> (%)
12.5	1096	639	58.51	-91	1098	638	16.33	-97	1058	662	13.50	-98
25	1617	433	7.79	-98	1559	449	5.51	-99	1782	393	4.57	-99
50	5275	133	2.81	-98	5116	137	2.25	-98	5254	133	2.21	-98
75	7539	93	1.66	-98	7625	92	1.61	-98	7565	93	1.56	-98

\*700 sccm F<sub>2</sub> injected into FRP

## Fluorine as a Function of Damper Position and Downstream Distance



## Fluorine Mass Balance at First Test Point

### 3.0 Feet Downstream

Damper Position (% Open)	Mass Balance (F <sub>in</sub> /F <sub>out</sub> )
12.5	21.4
25	17.4
50	35.3
75	37.8

\*90-95% of F detected as HF



## Duct Material Evaluation Results

Coupon #	Material	Other Identifier (Tradename etc.)	Initial Coupon Mass (g)	After F <sub>2</sub> Exposure (g)	After 10% HF Exposure (g)
1	PTFE	Teflon	8.74	8.74	8.74
2	FRP	Fiberglass reinforced plastic	5.13	5.13	5.29
3	FRPP	Flame retardant polypropylene Endura/Empee/Polyflam	7.92	7.92	7.92
4	PVC	Polyvinylchloride	12.38	12.36	12.36
5	PP	Polypropylene	8.04	8.02	8.02
6	ATS	ATS is a manufacturer of FRP using vinyl ester and phenolic resins	4.60	4.58	4.65
7	PVDF	polyvinylidenefluoride/Kynar	22.24	22.24	22.25
8	Flametec	Kytec-PVDF	17.88	17.88	17.89
9	Corzan	Corzan 4910 or CPVC	19.31	19.31	19.32
10	Halar	Halar ECTFE	15.92	15.94	15.92

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# Project Summary

- Industry trend toward NF<sub>3</sub>-based chamber cleans
- Measuring F<sub>2</sub> in an ambient air exhaust system is challenging
- F<sub>2</sub> conversion to HF is thermodynamically favored
  - >90% F<sub>2</sub> converted to HF—humidity is critical factor
  - Increased reaction time did not increase F<sub>2</sub> to HF conversion
- F<sub>2</sub> DRE increased above 98% with H<sub>2</sub>O-to-F<sub>2</sub> ratio >5-to-1
- Fluorine mass balance poor
  - Reaction on stainless steel and FRP wall surfaces may account for significant F<sub>2</sub> degradation
- FCS is a viable analytical technique for F<sub>2</sub> detection
  - more studies needed
- No OF<sub>2</sub> detected





# Future Work

- Publish International SEMATECH report
- Continue analytical testing of FCS
  - Perform surface analysis of substrates
- Use FCS to evaluate F<sub>2</sub> emissions from other processes



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